



Material Content Data Sheet



Sales Product Name		BSZ22DN20NS3 G		Issued		29. August 2013		
MA#		MA000862680						
Package		PG-TSDSON-8-1		Weight*		36.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.916	2.53	2.53	25307	25307
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		261	
	non noble metal	iron	7439-89-6	0.189	0.52		5230	
wire	non noble metal	copper	7440-50-8	7.689	21.24	21.80	212357	217913
	non noble metal	copper	7440-50-8	0.045	0.13	0.13	1256	1256
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1024
	plastics	epoxy resin	-	1.909	5.27		52727	
	inorganic material	silicondioxide	60676-86-0	16.589	45.81	51.18	458160	511911
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10221	10221
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2231	2231
solder	noble metal	silver	7440-22-4	0.030	0.08		821	
	non noble metal	tin	7440-31-5	0.024	0.07		657	
	non noble metal	lead	7439-92-1	1.135	3.14	3.29	31358	32836
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2596	
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.54	10.81	105391	108149
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2164	
	non noble metal	copper	7440-50-8	3.182	8.79	9.02	87877	90176
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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